



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification Number:	20260825000.0	Notification Issued	August 31, 2026
Datasheet for TLV906xS			

Change Type(s)	Data Sheet/Electrical Specification
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Notification Details

Description of Change:		
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.		
		TLV9061, TLV9062, TLV9064 SBOS839N – MARCH 2017 – REVISED JULY 2026
Changes from Revision M (December 2024) to Revision N (July 2026)		Page
• Changed the packaged dimensions of TLV9062S (YCK, DSBGA) to match package outline diagram		1
The datasheet number will be changing.		
Device Family	Change From:	Change To:
TLV906xS	SBOS839M	SBOS839N
These changes may be reviewed at the datasheet links provided.		
http://www.ti.com/product/TLV9061		
Reason for Change:	To accurately reflect device characteristics	
Anticipated impact on Form, Fit, Function, Quality or Reliability:	None	
Changes to product identification resulting from this PCN:	None	

Products Affected:			
TLV9062SIYCKR	TLV9062SIYCKR.A		

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS

Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

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